

IBM Docket No. JP920000096US1

wherein said liquid crystal driver tape carrier package and said circuit board have anchor holes, and

anchor pins are inserted into said anchor holes, whereby said liquid crystal driver tape carrier package is soldered to said circuit board via said anchor pins.

~~Cancel~~ claim 8.

REMARKS

In response to the Office Action dated December 18, 2002, applicants offer the following remarks addressing the outstanding Office Action.

Reconsideration is respectfully requested in view of the changes to the claims and the remarks herein.

In response to the Examiner's rejection of claims 4 – 9 under 35 U.S.C. § 102(e) as being anticipated by Muramatsu '838, applicants have amended claim 4 thereby making this rejection moot.

Applicants' claimed invention requires a " ... anchor pins are inserted into said anchor holes, whereby said liquid crystal driver tape carrier package is soldered to said circuit board via said anchor pins." Muramatsu does not teach the soldering of the TAB film and the printed circuit board via the anchor pins. To the contrary, Muramatsu uses press-fittings for the structure described in the patent, see column 11, line 63 – column 12, line 2.

Glaser fails to correct the deficiencies of the Muramatsu patent. Glaser fails to disclose or suggest, " ... anchor pins are inserted into said anchor holes, whereby said liquid crystal driver tape carrier package is soldered to said circuit board via said anchor pins." As a matter of fact, Glaser does not even disclose "anchor pins" as required in applicants' claims. What Glaser discloses are connector pins for an integrated circuit. Glaser further discloses the use of non-conductive insulated materials around the

Serial No. 09/681,674

2

IBM Docket No. JP920000096US1

connector pins, see column 3, lines 29 – 32. The use of non-conductive insulated materials is contrary to applicants' claimed invention that requires the use of the anchor pins to melt the solder around the anchor pin. There is no teachings or suggestions in Glaser to modify the fixing sections 48 of Muramatsu so as to have solder placed around them in a fashion like applicants' claimed invention. Therefore, the claims are not made obvious by Muramatsu in view of Glaser or Yamagishi because Glaser lacks the teachings, the suggestions and the motivations to make the required structural changes to Muramatsu to make obvious in applicants' claims.

Applicants notes the prior art cited but not applied by the Examiner and agrees that they do not disclose or make obvious the claimed invention.

In view of the changes to the claims and the remarks herein, applicants believe that the application is now condition for allowance and respectfully request the Examiner to reconsider and allow the above-identified application. If the Examiner wishes to discuss the application further, or if additional information would be required, the undersigned will cooperate fully to assist in the prosecution of this application.

Please charge any fee necessary to enter this paper and any previous paper to deposit account 09-0468.

Serial No. 09/681,674

3

IBM Docket No. JP920000096US1

In the event that this amendment does not result in allowance of all such claims, the undersigned respectfully requests a telephone interview at the Examiner's earliest convenience.

Respectfully submitted,

By:


Derek S. Jennings
Registered Patent Agent / Patent Engineer
Reg. No. 41,473

IBM Corporation
Intellectual Property Law Department
P. O. Box 218
Yorktown Heights, New York 10598
Telephone No.: (914) 945-2144

FAX RECEIVED

MAR 18 2003

TECHNOLOGY CENTER 2800

Serial No. 09/681,674

4

IBM Docket No. JP920000096US1

Marked up changes for the claims:

4. (Amended) A liquid crystal display device comprising:
- a pair of glass substrates facing each other, each having electrodes for applying voltage to a liquid crystal material on a facing surface;
 - a circuit board for supplying said voltage; and
 - a liquid crystal driver tape carrier package for connecting said electrodes of said glass substrates to said circuit board and mounting a liquid crystal driver chip,
- wherein said liquid crystal driver tape carrier package and said circuit board have anchor holes, and
- anchor pins are inserted into said anchor holes, whereby said liquid crystal driver tape carrier package is soldered to said circuit board via said anchor pins [. said liquid crystal driver tape carrier package is fixed to said circuit board].

Serial No. 09/681,674

5